

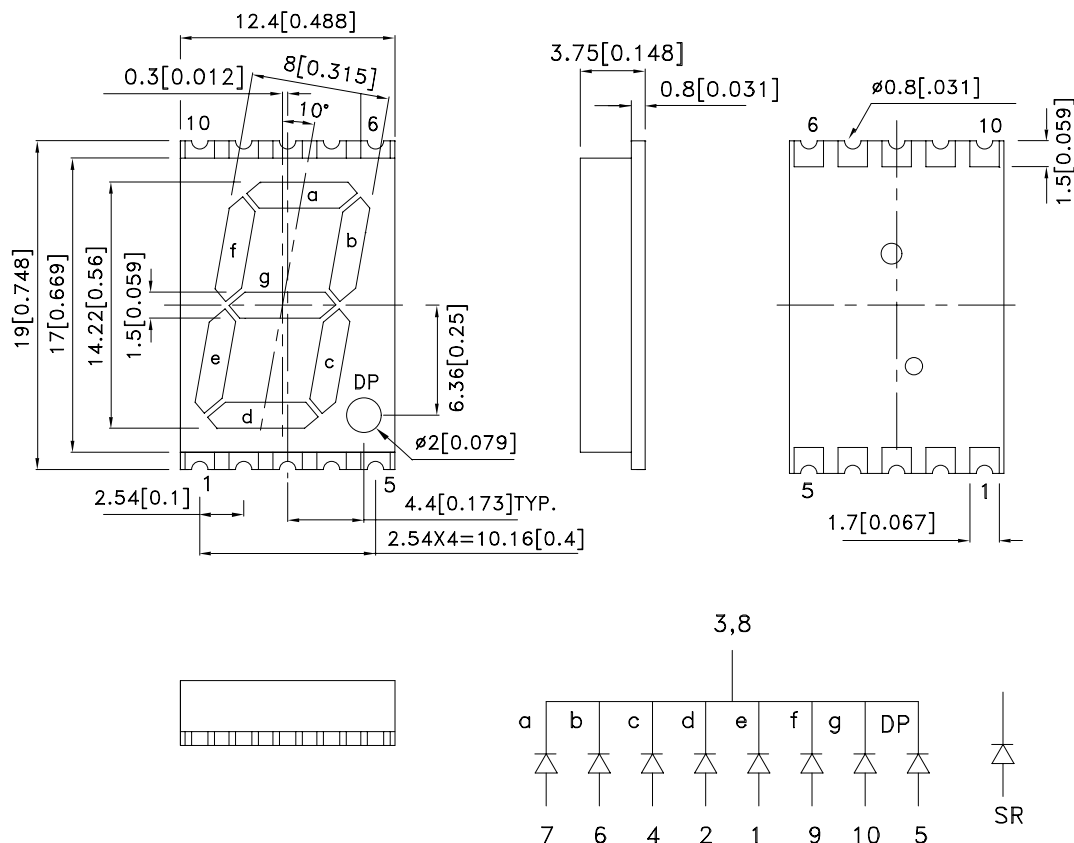
Features

- 0.56 INCH DIGIT HEIGHT.
- LOW CURRENT OPERATION.
- EXCELLENT CHARACTER APPEARANCE.
- I.C. COMPATIBLE.
- MECHANICALLY RUGGED.
- GRAY FACE, WHITE SEGMENT.
- PACKAGE: 400 PCS/ REEL.
- MOISTURE SENSITIVITY LEVEL : LEVEL 4.
- RoHS COMPLIANT.

Description

The Super Bright Red source color devices are made with Gallium Aluminum Arsenide Red Light Emitting Diode.

Package Dimensions & Internal Circuit Diagram



Notes:

1. All dimensions are in millimeters (inches). Tolerance is $\pm 0.25 (0.01)$ unless otherwise noted.
2. Specifications are subject to change without notice.
3. The gap between the reflector and PCB shall not exceed 0.25mm



Selection Guide

Part No.	Dice	Lens Type	Iv (ucd) [1] @ 10mA		Description
			Min.	Typ.	
KCSC56-104	SUPER BRIGHT RED (GaAlAs)	WHITE DIFFUSED	8000	26000	Common Cathode, Rt. Hand Decimal.

Note:

1. Luminous Intensity / Luminous Flux: +/-15%.

Electrical / Optical Characteristics at TA=25°C

Symbol	Parameter	Device	Typ.	Max.	Units	Test Conditions
λ_{peak}	Peak Wavelength	Super Bright Red	660		nm	IF=20mA
λ_D [1]	Dominant Wavelength	Super Bright Red	640		nm	IF=20mA
$\Delta\lambda_{1/2}$	Spectral Line Half-width	Super Bright Red	20		nm	IF=20mA
C	Capacitance	Super Bright Red	45		pF	VF=0V;f=1MHz
VF [2]	Forward Voltage	Super Bright Red	1.85	2.5	V	IF=20mA
IR	Reverse Current	Super Bright Red		10	uA	VR=5V

Notes:

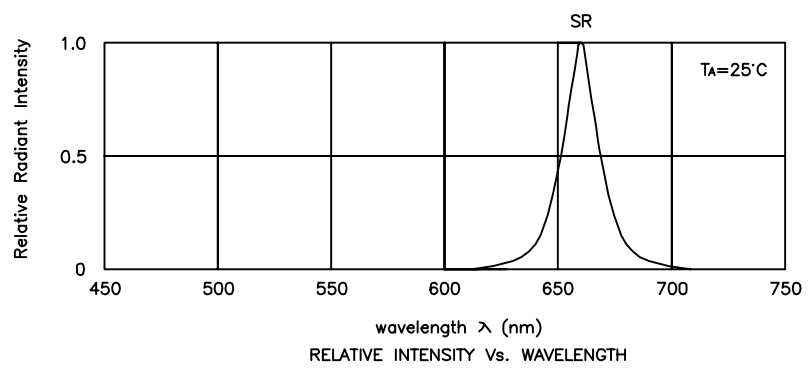
1. Wavelength: +/-1nm.

Absolute Maximum Ratings at TA=25°C

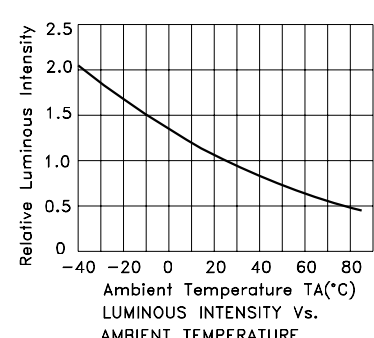
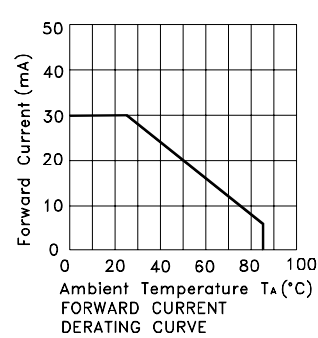
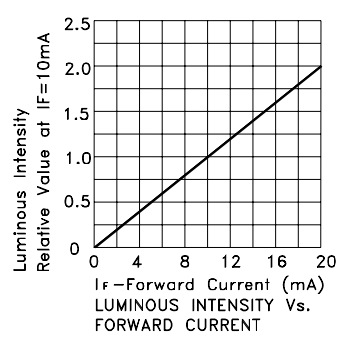
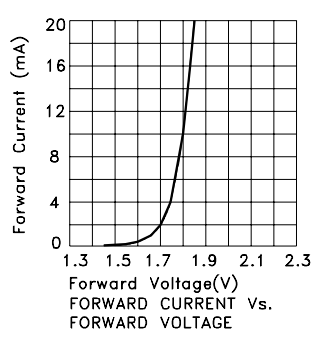
Parameter	Super Bright Red	Units
Power dissipation	75	mW
DC Forward Current	30	mA
Peak Forward Current [1]	155	mA
Reverse Voltage	5	V
Operating / Storage Temperature	-40°C To +85°C	

Note:

1. 1/10 Duty Cycle, 0.1ms Pulse Width.

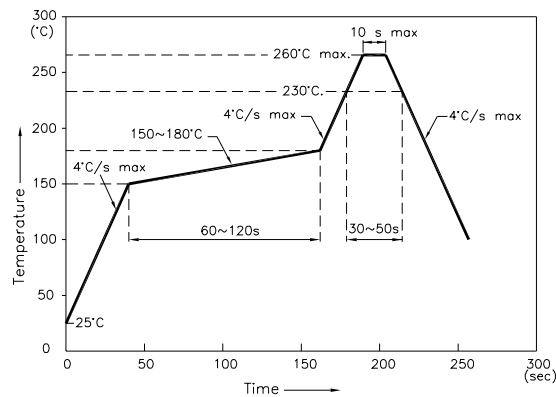


Super Bright Red KCSC56-104



KCSC56-104

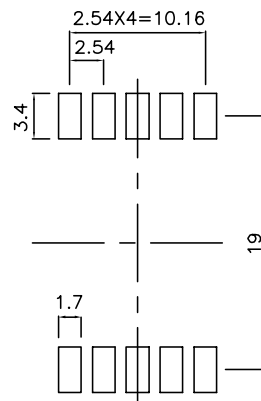
Reflow Soldering Profile For Lead-free SMT Process.



NOTES:

1. We recommend the reflow temperature 245°C(+/-5°C). The maximum soldering temperature should be limited to 260°C.
2. Don't cause stress to the epoxy resin while it is exposed to high temperature.
3. Number of reflow process shall be 2 times or less.

Recommended Soldering Pattern (Units: mm ; Tolerance: ± 0.15)



Tape Specifications (Units : mm)

